ABSTRACT

APPARATUS AND METHOD FOR ARRANGING DEVICES FOR PROCESSING

An apparatus is provided for arranging for processing a semiconductor device having surface components on its surface. A device support comprising a set of protrusions for contacting a surface of the semiconductor device supports the semiconductor device on a plane. The protrusions are arranged and positioned such that they avoid contact with the surface components on the surface. In order to grip the semiconductor device supported on the plane, a clamping device having a first set of clamps is configured for gripping the semiconductor device along a first axis and a second set of clamps is configured for gripping the semiconductor device along a second axis perpendicular to the first axis.

(FIG. 2A)